

XP0D874 (XP1D874)

N-channel junction FET

For low-frequency impedance conversion

For infrared sensor

■ Features

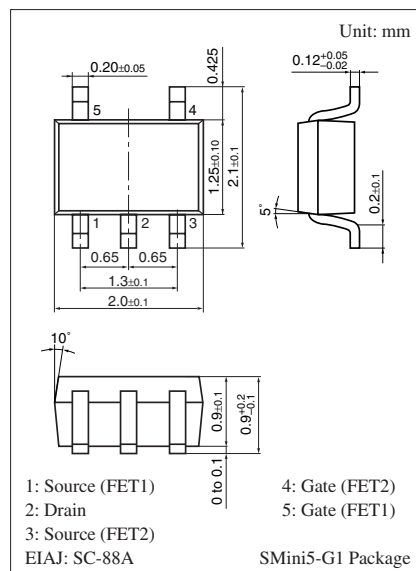
- Two elements incorporated into one package
- Reduction of the mounting area and assembly cost by one half

■ Basic Part Number

- 2SK1842 × 2

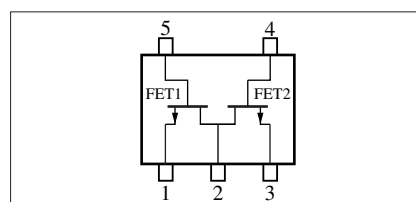
■ Absolute Maximum Ratings $T_a = 25^\circ\text{C}$

Parameter	Symbol	Rating	Unit
Gate-drain voltage (Source open)	V_{GDO}	-40	V
Gate-source voltage (Drain open)	V_{GSO}	-40	V
Drain current	I_D	1	mA
Gate current	I_G	10	mA
Total power dissipation	P_T	150	mW
Channel temperature	T_{ch}	150	$^\circ\text{C}$
Storage temperature	T_{stg}	-55 to +150	$^\circ\text{C}$



Marking Symbol: EQ

Internal Connection

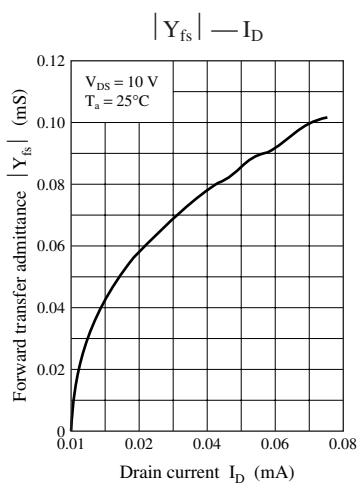
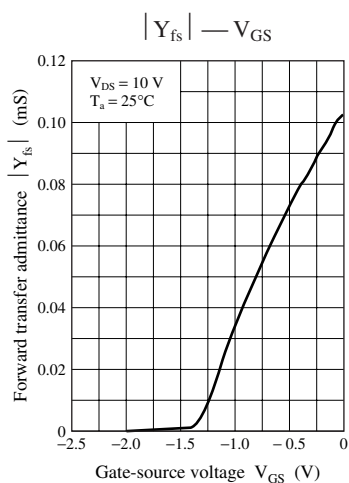
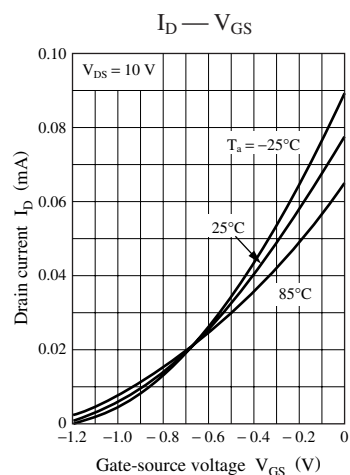
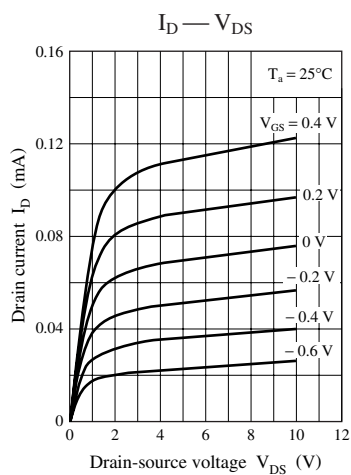
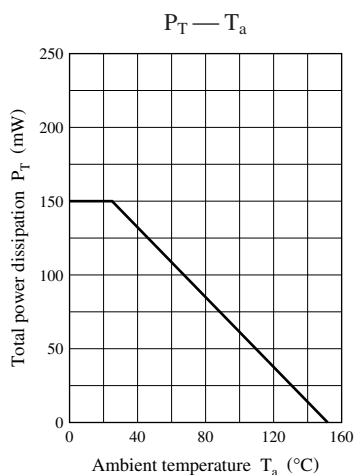


■ Electrical Characteristics $T_a = 25^\circ\text{C} \pm 3^\circ\text{C}$

Parameter	Symbol	Conditions	Min	Typ	Max	Unit
Gate-drain surrender voltage	V_{GDS}	$I_G = -10 \mu\text{A}$, $V_{DS} = 0$	-40			V
Drain-source cutoff current	I_{DSS}	$V_{DS} = 10 \text{ V}$, $V_{GS} = 0$	30		200	μA
Gate-source cutoff current	I_{GSS}	$V_{GS} = -20 \text{ V}$, $V_{DS} = 0$			-0.5	nA
Gate-source cutoff voltage	V_{GSC}	$V_{DS} = 10 \text{ V}$, $I_D = 1 \mu\text{A}$		-1.3	-3.0	V
Forward transfer admittance	$ Y_{fs} $	$V_{DS} = 10 \text{ V}$, $V_{GS} = 0$, $f = 1 \text{ KHz}$	0.05			mS
Short-circuit forward transfer capacitance (Common-source)	C_{iss}	$V_{DS} = 10 \text{ V}$, $V_{GS} = 0$, $f = 1 \text{ MHz}$		1.0		pF
Short-circuit output capacitance (Common-source)	C_{oss}			0.4		pF
Reverse transfer capacitance (Common-source)	C_{rss}			0.4		pF

Note) Measuring methods are based on JAPANESE INDUSTRIAL STANDARD JIS C 7030 Measuring methods for transistors.

Note) The part number in the parenthesis shows conventional part number.



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